IPC - ASSOCIATION CONN ELECTRONICS INDUS	© Copyright 2005. II	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information				
upplier Info	ormation Section								,					
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi											2024-05-18			
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			I	Phone - Representative*				Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requ	uester Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	Version Manufacturing Site		V	Veight*	UOM	Unit Type
		NTMFS5C604NLT1G NFET SO8FL 60		NFET SO8FL 60V	289A 1.2MO	89A 1.2MO 2024-			N	MY1		05.95	mg	Each
	ing Process Informat		omnimal Daga	Allow	STD-020 MS	I. Dotino	Dools Duo	aga Dody T	· ·	May Time at Pack	Tommount	Myssila North	er of Reflow Cyc	alac
			Terminal Base Alloy J-ST CU Alloy 1		S I D-020 MS	L Kating	260	ss Body Temperature Max Time at Peak C 30		seconds 3		er of Reflow Cyc	cies	
•	te 1111 (511) - anneated	C	U Alloy	I			200		<u>IC</u>	30	second	18 3		
omments	um time at week tow	uo duuina1	domina ia 10 2	O soconda										
	um time at peak temperatu													
r more infort	mation regarding material	composition j	piease reter to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itability and the Company's remedies for issues that arise regarding information the Supplier provides in this f										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	4.8	mg	Supplier	Iron (Fe)	7439-89-6		0.0048	mg
			Supplier	Copper (Cu)	7440-50-8		4.7938	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0014	mg
Die	0.61	mg	Supplier	Silicon (Si)	7440-21-3		0.61	mg
Die Attach Solder	1.99	mg	Supplier	Silver (Ag)	7440-22-4		0.0498	mg
			A	Lead (Pb)	7439-92-1	7a	1.8407	mg
			Supplier	Tin (Sn)	7440-31-5		0.0995	mg
Lead Frame	47.6	mg	Supplier	Silver (Ag)	7440-22-4		0.0286	mg
			Supplier	Iron (Fe)	7439-89-6		0.0476	mg
			Supplier	Copper (Cu)	7440-50-8		47.5096	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0143	mg
Mold Compound-Black	49.2	mg		Epoxy resin	proprietary data		3.69	mg
			Supplier	Phenolic Resin	Proprietary Data		1.23	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.69	mg
			Supplier	Carbon Black (C)	1333-86-4		0.246	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		40.344	mg
Plating	1.7	mg	Supplier	Tin (Sn)	7440-31-5		1.7	mg
Wire Bond - Cu	0.05	mg	Supplier	Copper (Cu)	7440-50-8		0.05	mg